

US 20240237199A9

## (19) United States

# (12) Patent Application Publication PARK et al.

## (10) Pub. No.: US 2024/0237199 A9

# (48) Pub. Date: Jul. 11, 2024 CORRECTED PUBLICATION

### (54) ELECTRONIC SUBSTRATE

(71) Applicant: LG INNOTEK CO., LTD., Seoul (KR)

(72) Inventors: **Heun PARK**, Seoul (KR); **Kab Young KIM**, Seoul (KR); **Sang Young LEE**,

Seoul (KR)

(73) Assignee: LG INNOTEK CO., LTD., Seoul (KR)

(21) Appl. No.: 18/278,967

(22) PCT Filed: Feb. 25, 2022

(86) PCT No.: PCT/KR2022/002763

§ 371 (c)(1),

(2) Date: Aug. 25, 2023

#### **Prior Publication Data**

(15) Correction of US 2024/0138058 A1 Apr. 25, 2024See (22) PCT Filed.See (86) PCT No.See (30) Foreign Application Priority Data.

(65) US 2024/0138058 A1 Apr. 25, 2024

(30) Foreign Application Priority Data

Feb. 26, 2021 (KR) ...... 10-2021-0026518

#### **Publication Classification**

(51)	Int. Cl.	
	H05K 1/02	(2006.01)
	H05K 1/03	(2006.01)
	H05K 1/11	(2006.01)
	H05K 1/18	(2006.01)

### (57) ABSTRACT

According to one embodiment of the present invention, an electronic substrate includes a base including a first surface and a second surface that is a surface opposite to the first surface, an electronic component disposed on the second surface of the base, and a line disposed on the second surface of the base and connected to the electronic component, wherein the base includes a frame region including a flexible material and a plurality of opening regions passing between the first surface and the second surface, and the electronic component and the line are disposed in the frame region.



